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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ray *et al.*

Examiner: Nguyen, Ha T

Serial No.: 09/779,812

Art Unit: 2812

Filed: 2/08/01

For: **LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

Commissioner for Patents  
Washington D.C. 20231

Sir:

This paper is being filed in response to the Office Action mailed June 14, 2002. Applicants respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

**Amendment**

Please amend the above-referenced patent application as follows:

**In the Claims:**

Please amend claims 25-29 as marked up in Appendix A. Please add new claims 35-36.

Pending claims 1-10 and 12-36 are as follows based on the amendment herein:

1. A method for forming an electronic structure, comprising the steps of:  
providing a substrate; and

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